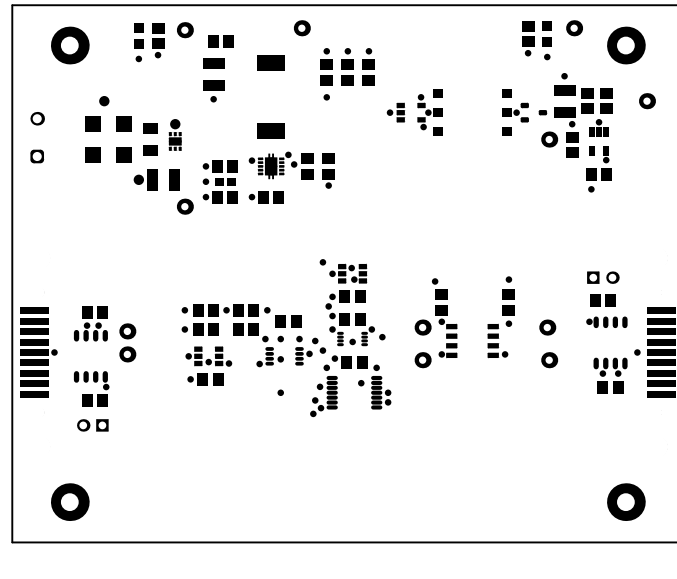
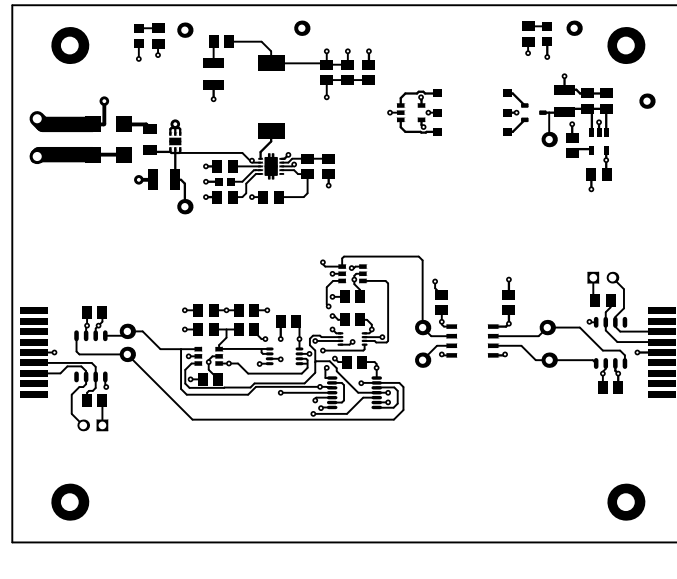


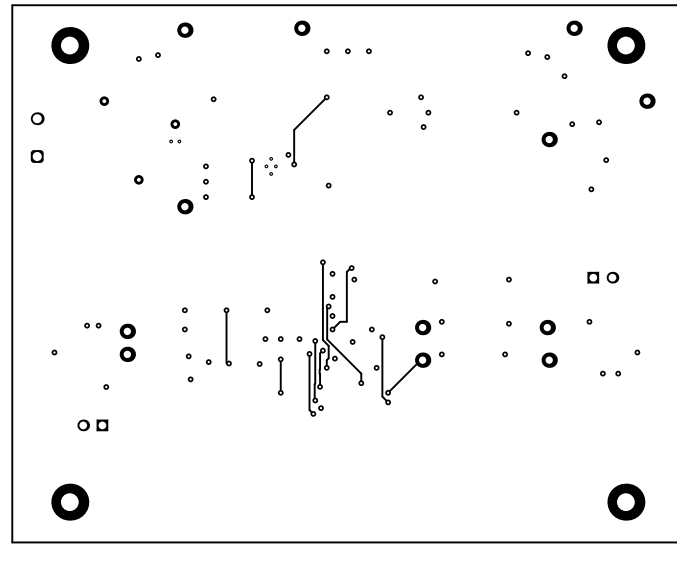
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01487	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01487		
PLOT NAME = Top Overlay	GENERATED : 3/12/2018 1:04:34 PM	TEXAS INSTRUMENTS	



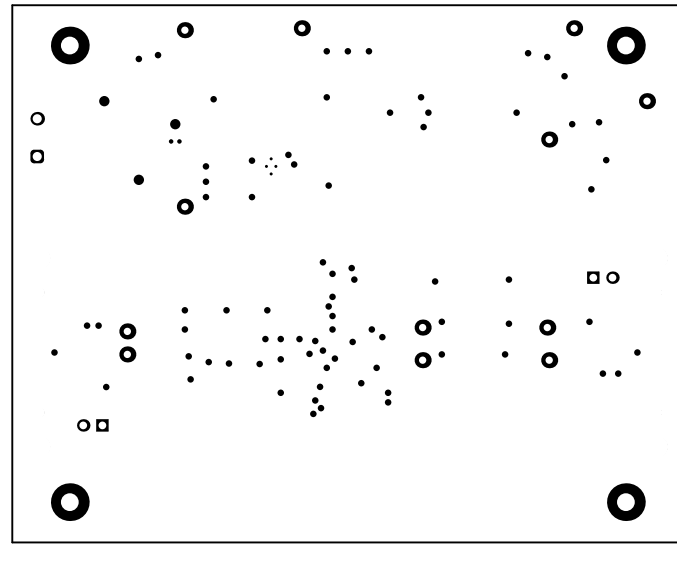
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01487	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01487		
PLOT NAME = Top Solder Mask	GENERATED : 3/12/2018 1:04:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01487	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01487		
PLOT NAME = Top Layer	GENERATED : 3/12/2018 1:04:36 PM	TEXAS INSTRUMENTS	



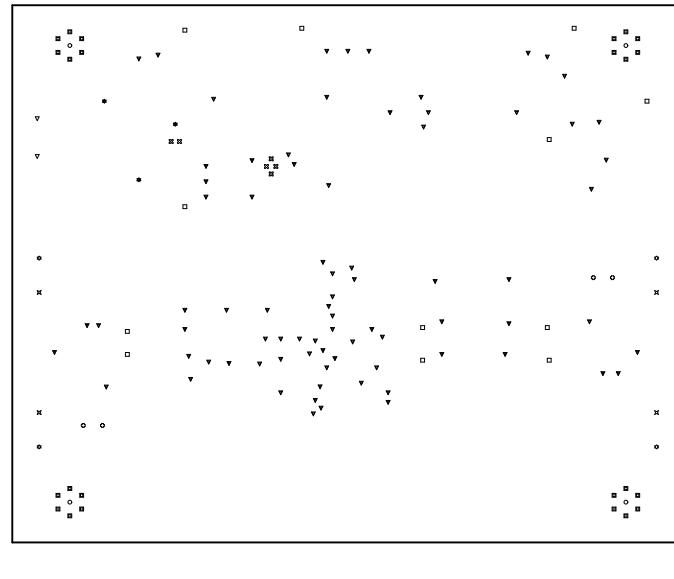
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01487	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01487		
PLOT NAME = Bottom Layer	GENERATED : 3/12/2018 1:04:37 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01487	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01487		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/12/2018 1:04:38 PM	TEXAS INSTRUMENTS	

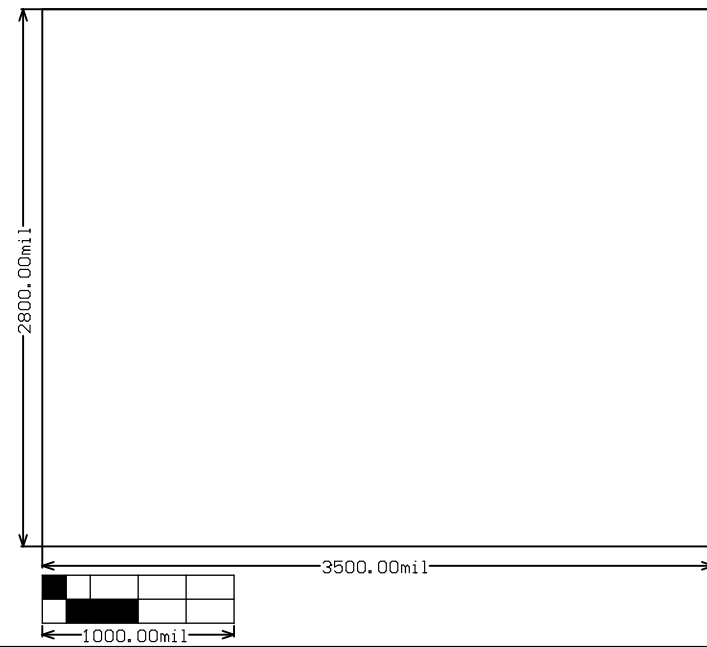


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01487	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01487		
PLOT NAME = Bottom Overlay	GENERATED : 3/12/2018 1:04:39 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	4	59.00mil (1.499mm)	NPTH	Round	Top Layer - Bottom Layer	
⊛	4	120.00mil (3.048mm)	NPTH	Round	Top Layer - Bottom Layer	
⊞	6	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
▼	79	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
■	24	19.69mil (0.500mm)	PTH	Round	Top Layer - Bottom Layer	
★	3	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
□	12	37.99mil (0.965mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	4	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	92.52mil (2.350mm)	PTH	Round	Top Layer - Bottom Layer	
	142 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01487	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01487		
PLOT NAME = Drill Drawing	GENERATED : 3/12/2018	1:04:39 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01487	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01487		
PLOT NAME = Board Dimensions	GENERATED : 3/12/2018 1:04:41 PM	TEXAS INSTRUMENTS	



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